

HD74HC375

Quad. Bistable Latches

REJ03D0621-0200
 (Previous ADE-205-500)
 Rev.2.00
 Mar 30, 2006

Description

This latch is ideally suited for use as temporary storage for binary information between processing units and input/output or indicator units. Information present at a data (D) input is transferred to the Q output when the enable (G) is high and the Q output will follow the data input as long as the enable remains high. When the enable goes low, the information (that was present at the data input at the time the transition occurred) is retained at the Q output until the enable goes high.

Features

- High Speed Operation: t_{pd} (Data to Q, \bar{Q}) = 10 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)
- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74HC375P	DILP-16 pin	PRDP0016AE-B (DP-16FV)	P	—
HD74HC375FPEL	SOP-16 pin (JEITA)	PRSP0016DH-B (FP-16DAV)	FP	EL (2,000 pcs/reel)
HD74HC375RPEL	SOP-16 pin (JEDEC)	PRSP0016DG-A (FP-16DNV)	RP	EL (2,500 pcs/reel)

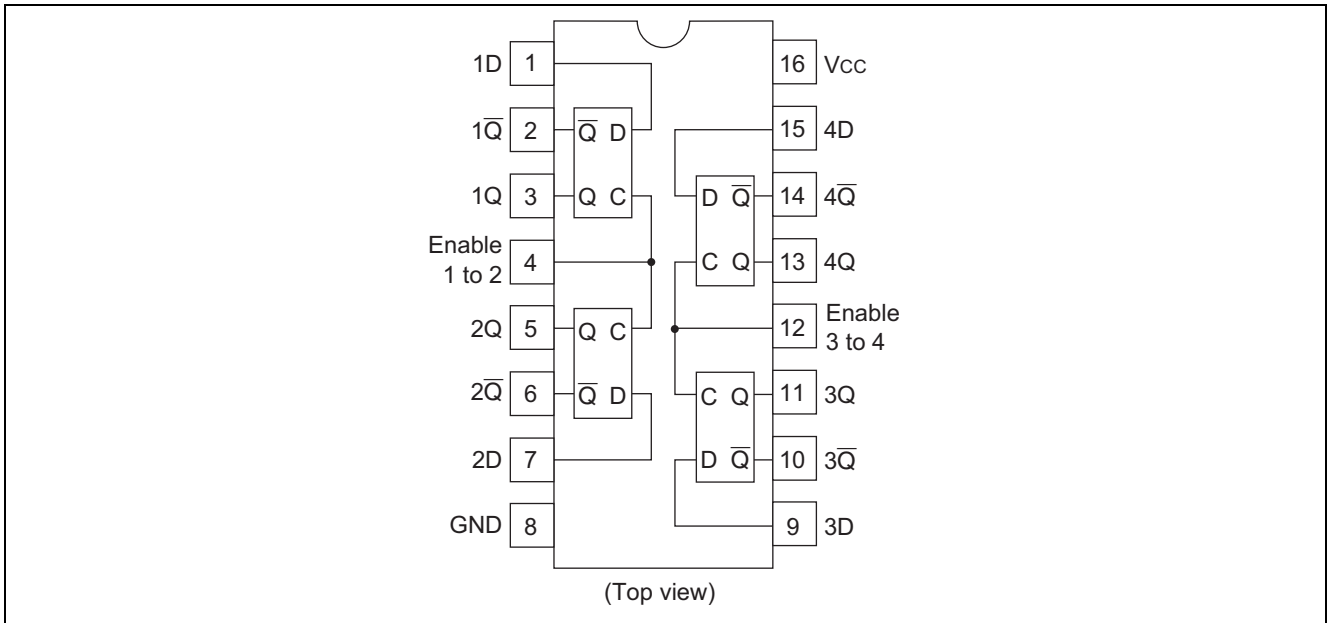
Note: Please consult the sales office for the above package availability.

Function Table

Inputs		Outputs	
D	G	Q	\bar{Q}
L	H	L	H
H	H	H	L
X	L	no change	no change

Note: 1. H; High level, L; Low level, X; Irrelevant, Z; High impedance

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage range	V_{CC}	-0.5 to 7.0	V
Input / Output voltage	V_{IN}, V_{OUT}	-0.5 to $V_{CC} + 0.5$	V
Input / Output diode current	I_{IK}, I_{OK}	± 20	mA
Output current	I_{OUT}	± 25	mA
V_{CC} , GND current	I_{CC} or I_{GND}	± 50	mA
Power dissipation	P_T	500	mW
Storage temperature	T_{stg}	-65 to +150	$^{\circ}C$

Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	2 to 6	V	
Input / Output voltage	V_{IN}, V_{OUT}	0 to V_{CC}	V	
Operating temperature	T_a	-40 to 85	$^{\circ}C$	
Input rise / fall time*1	t_r, t_f	0 to 1000	ns	$V_{CC} = 2.0 V$
		0 to 500		$V_{CC} = 4.5 V$
		0 to 400		$V_{CC} = 6.0 V$

Note: 1. This item guarantees maximum limit when one input switches.
Waveform: Refer to test circuit of switching characteristics.

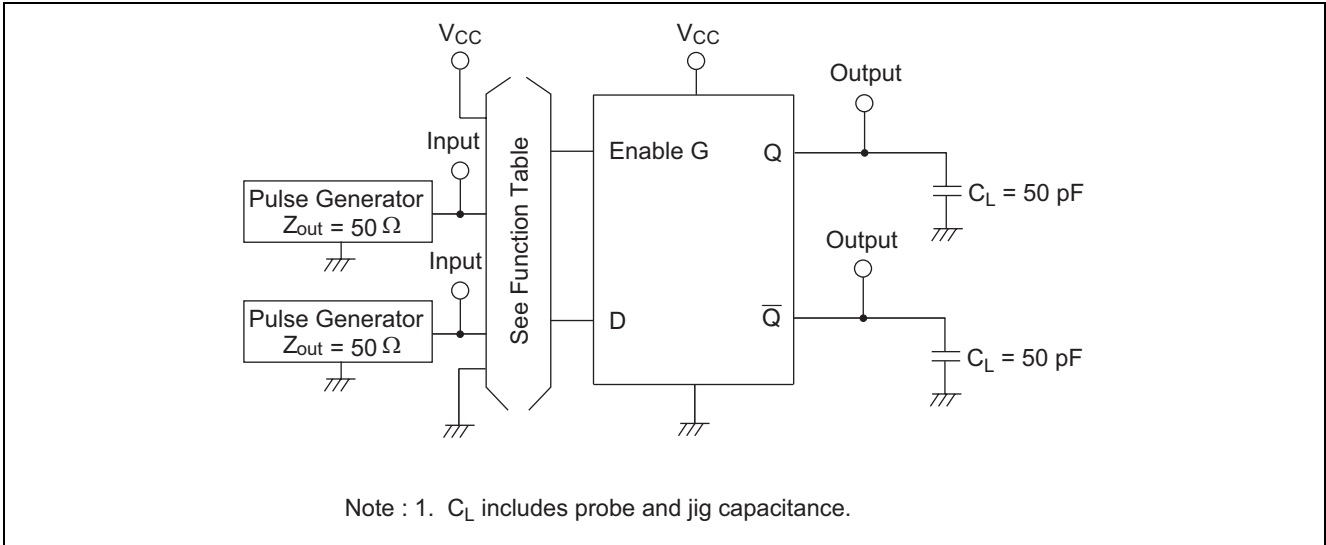
Electrical Characteristics

Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL}	I _{OH} = -20 μA
		4.5	4.4	4.5	—	4.4	—			I _{OH} = -4 mA
		6.0	5.9	6.0	—	5.9	—			I _{OH} = -5.2 mA
		4.5	4.18	—	—	4.13	—			
		6.0	5.68	—	—	5.63	—			
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL}	I _{OL} = 20 μA
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OH} = 4 mA
		6.0	—	—	0.26	—	0.33			I _{OH} = 5.2 mA
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, I _{out} = 0 μA	

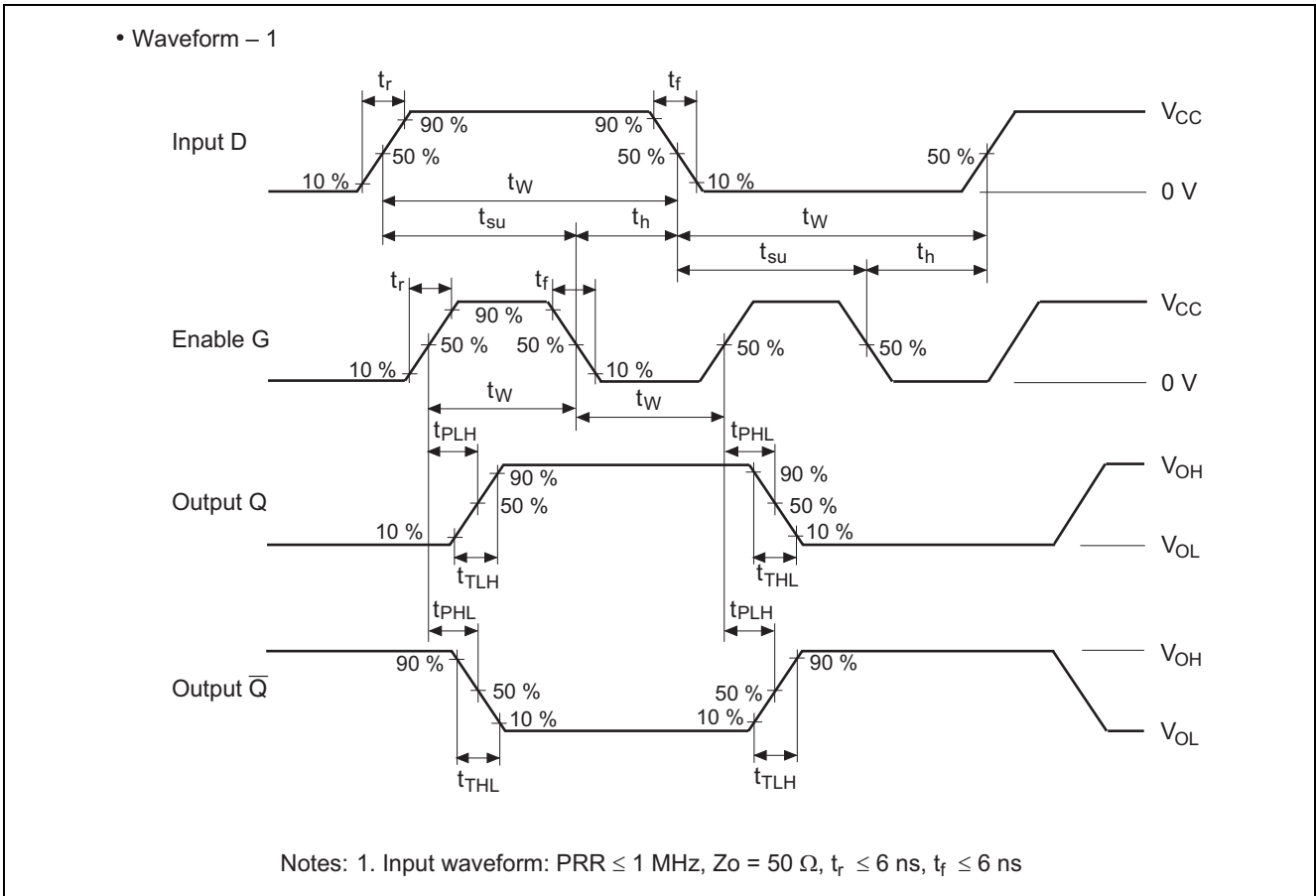
Switching Characteristics (C_L = 50 pF, Input t_r = t_f = 6 ns)

Item	Symbol	V _{CC} (V)	Ta = 25°C			Ta = -40 to +85°C		Unit	Test Conditions	
			Min	Typ	Max	Min	Max			
Propagation delay time	t _{PLH}	2.0	—	—	145	—	180	ns	Data to Q or \bar{Q}	
		4.5	—	10	29	—	36			
		6.0	—	—	25	—	31			
	t _{PHL}	2.0	—	—	160	—	200	ns	G to Q or \bar{Q}	
		4.5	—	11	32	—	40			
		6.0	—	—	27	—	34			
Pulse width	t _w	2.0	80	—	—	100	—	ns		
		4.5	16	5	—	20	—			
		6.0	14	—	—	17	—			
Setup time	t _{su}	2.0	100	—	—	125	—	ns		
		4.5	20	2	—	25	—			
		6.0	17	—	—	21	—			
Hold time	t _h	2.0	5	—	—	5	—	ns		
		4.5	5	-1	—	5	—			
		6.0	5	—	—	5	—			
Output rise/fall time	t _{TLH} t _{THL}	2.0	—	—	75	—	95	ns		
		4.5	—	5	15	—	19			
		6.0	—	—	13	—	16			
Input capacitance	C _{in}	—	—	5	10	—	10	pF		

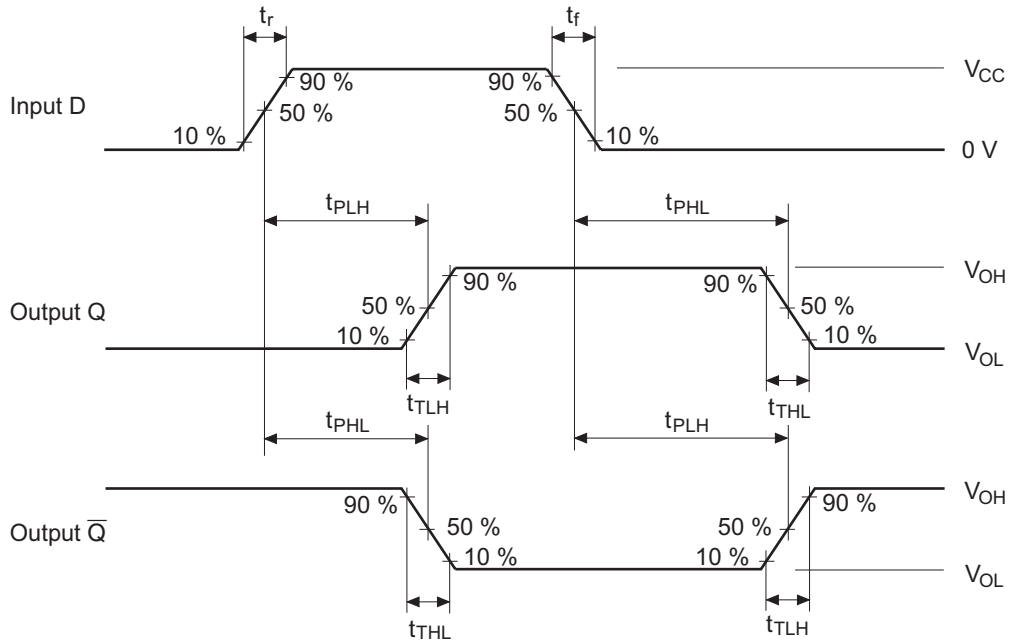
Test Circuit



Waveforms



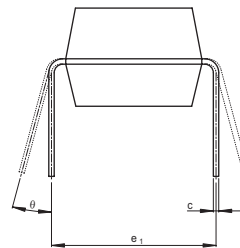
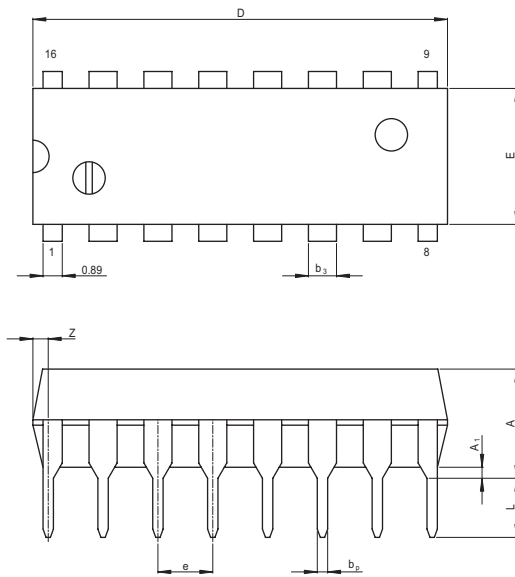
• Waveform – 2



Note: 1. Input waveform: $PRR \leq 1 \text{ MHz}$, $Z_o = 50 \Omega$, $t_r \leq 6 \text{ ns}$, $t_f \leq 6 \text{ ns}$

Package Dimensions

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-DIP16-6.3x19.2-2.54	PRDP0016AE-B	DP-16FV	1.05g

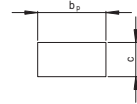
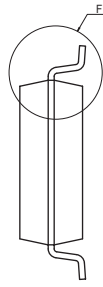
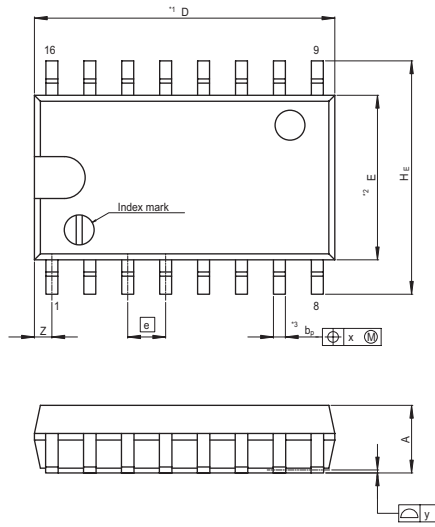


(NiPd/Au plating)

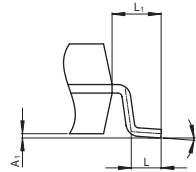
Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
e_1	—	7.62	—
D	—	19.2	20.32
E	—	6.3	7.4
A	—	—	5.06
A_1	0.51	—	—
b_p	0.40	0.48	0.56
b_3	—	1.30	—
c	0.19	0.25	0.31
θ	0°	—	15°
e	2.29	2.54	2.79
Z	—	—	1.12
L	2.54	—	—

HD74HC375

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP16-5.5x10.06-1.27	PRSP0016DH-B	FP-16DAV	0.24g



Terminal cross section
(Ni/Pd/Au plating)

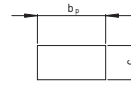
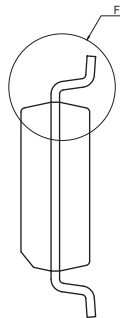
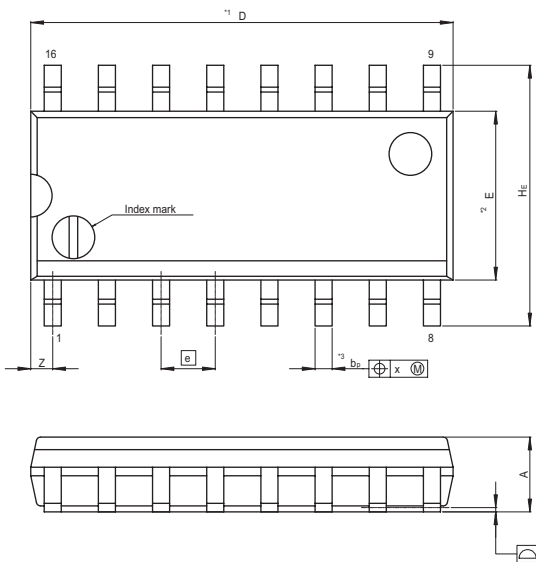


Detail F

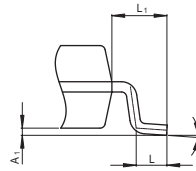
NOTE)
1. DIMENSIONS**1 (Nom)**AND**2*
DO NOT INCLUDE MOLD FLASH.
2. DIMENSION**3*DOES NOT
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	10.06	10.5
E	—	5.50	—
A ₂	—	—	—
A ₁	0.00	0.10	0.20
A	—	—	2.20
b _P	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	7.50	7.80	8.00
e	—	1.27	—
x	—	—	0.12
y	—	—	0.15
Z	—	—	0.80
L	0.50	0.70	0.90
L ₁	—	1.15	—

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-SOP16-3.95x9.9-1.27	PRSP0016DG-A	FP-16DNV	0.15g



Terminal cross section
(Ni/Pd/Au plating)



Detail F

NOTE)
1. DIMENSIONS**1 (Nom)**AND**2*
DO NOT INCLUDE MOLD FLASH.
2. DIMENSION**3*DOES NOT
INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	9.90	10.30
E	—	3.95	—
A ₂	—	—	—
A ₁	0.10	0.14	0.25
A	—	—	1.75
b _P	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	5.80	6.10	6.20
e	—	1.27	—
x	—	—	0.25
y	—	—	0.15
Z	—	—	0.635
L	0.40	0.60	1.27
L ₁	—	1.08	—

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